L Number	Hits	Search Text	DB	Time stamp
1	21	alignment adj tolerance adj range	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:21
3	150	(alignment adj tolerance) and (common adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:39
4	10	(alignment adj tolerance) and (common adj carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:31
5.	7	first adj alignment adj tolerance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:36
6	9	second adj alignment adj tolerance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:36
7	642	(alignment adj tolerance) and (package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:41
8	46	(alignment adj tolerance) and (integrated adj chips)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:43
9	178	(alignment adj tolerance) and (integrated adj circuit adj chips)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:49
10	10	(alignment adj tolerance) and (plurality adj packages)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 15:08
11	18	(alignment adj tolerance) and (plurality near packages)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 15:08
-	2	4254445.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:35
-	2	6163068.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:47
-	2	6362117.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:52
-	3	4326180.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:52

-	14	(common adj carrier) and (integrated adj chips) and (substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:57
-	7	(common adj carrier) with (integrated adj circuit adj chips)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 17:59
-	41	(common adj carrier) with (integrated adj circuits)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:03
-	19	(common adj carrier) with (ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:13
-	8	(common adj carrier) and 257/685.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:30
-	471	257/685.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 09:32
-	6	integrated adj chip adj array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 18:35
-	894	integrated adj circuit adj array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 11:45
-	783	package adj array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 11:56
-	291	(integrated adj circuit adj array) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 11:46
-	307	(package adj array) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 12:27
-	707	(chip adj array) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/19 12:33
-	117	(semiconductor adj chip adj array) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 09:18
-	1907	257/723.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 10:15

-		6	747966.pn.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 14:14